

# SOT1321-1

plastic thin fine-pitch ball grid array package; 132 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA132
<b>Package type industry code</b>	TFBGA132
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-205
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	25-1-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	0.95	-	1.05	1.2	mm
A <sub>2</sub>	package height	0.65	-	0.7	0.8	mm
e	nominal pitch	-	-	0.8	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	132	-	

## 2. Package outline

Fig. 1. Package outline TFBGA132 (SOT1321-1)



### 3. Legal information

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Date of release: 8 February 2016

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